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TRANSMITTAL			Application Number		April 13, 2000		
_	\ L=	Filing Date First Named Inventor		Estacio, Maria Cristina B.			
FORM	Group Art Unit		2811 N. Parekh				
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and Reg. No 85,933							
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ATTENTION:

Examiner N. Parekh

TELEPHONE NO.:

1 703 308-2772

Group Art Whit 2811

## OFFICIAL COMMUNICATION

# FOR THE PERSONAL ATTENTION OF

## **EXAMINER N. Parekh**

### CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following document(s) in re Application of Maria Christine B. Estacio, Application No. 09/548,946, filed April 13, 2000 for FLIP CLIP ATTACH AND COPPER CLIP ATTACH ON MOSFET DEVICE is being facsimile transmitted to the Patent and Trademark Office on the date shown below.

#### Document(s) Attached

1. Trasnmittal Form

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Amendment

NOV 29 2001

Number of pages being transmitted, including this page: 8

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**2**003/008

Attorney Docket No.: 018865-004500US

Client Ref. No.: 17732-1394

# IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Maria Christine B. Estacio

Application No.: 09/548,946

Filed: April 13, 2000

For: FLIP CLIP ATTACH AND COPPER CLIP ATTACH ON MOSFET

DEVICE

Examiner:

N. Parekh

Art Unit:

2811

AMENDMENT

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NOV 29 2001

TECHNOLOGY CENTER 2800

Assistant Commissioner for Patents Washington, D.C. 20231

Sir:

In response to the Office Action mailed August 29, 2001, please amend the above-identified application as follows:

#### IN THE CLAIMS:

Please cancel claims 1-4.

Please amend the following claim:

(Amended) Achip device comprising:

a leadframe including source and gate connections;

a bumped die including solder bumps on a top side, the bumped die being

attached to the leadframe such that the solder bumps contact the source and gate

connections; and

a copper clip attached to a backside of the bumped die such that the copper clip contacts drain regions of the bumped die and a lead rail.